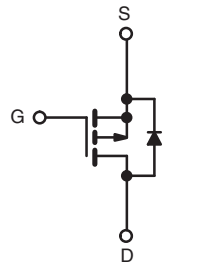
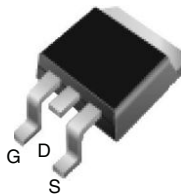


## Power MOSFET

PRODUCT SUMMARY	
$V_{DS}$ (V)	- 100
$R_{DS(on)}$ ( $\Omega$ )	$V_{GS} = -10$ V   1.2
$Q_g$ (Max.) (nC)	8.7
$Q_{gs}$ (nC)	2.2
$Q_{gd}$ (nC)	4.1
Configuration	Single

**D<sup>2</sup>PAK (TO-263)**


P-Channel MOSFET

### FEATURES

- Halogen-free According to IEC 61249-2-21 Definition
- Surface Mount
- Available in Tape and Reel
- Dynamic  $dV/dt$  Rating
- Repetitive Avalanche Rated
- P-Channel
- 175 °C Operating Temperature
- Fast Switching
- Compliant to RoHS Directive 2002/95/EC



**RoHS\***  
COMPLIANT  
HALOGEN  
**FREE**  
Available

### DESCRIPTION

Third generation Power MOSFETs from Vishay provide the designer with the best combination of fast switching, ruggedized device design, low on-resistance and cost-effectiveness.

The D<sup>2</sup>PAK (TO-263) is a surface mount power package capable of accommodating die size up to HEX-4. It provides the highest power capability and the lowest possible on-resistance in any existing surface mount package. The D<sup>2</sup>PAK (TO-263) is suitable for high current applications because of its low internal connection resistance and can dissipate up to 2.0 W in a typical surface mount application.

ORDERING INFORMATION		
Package	D <sup>2</sup> PAK (TO-263)	D <sup>2</sup> PAK (TO-263)
Lead (Pb)-free and Halogen-free	SiHF9510S-GE3	SiHF9510STRL-GE3 <sup>a</sup>
Lead (Pb)-free	IRF9510SPbF	IRF9510STRLPbF <sup>a</sup>
	SiHF9510S-E3	SiHF9510STL-E3 <sup>a</sup>

**Note**

a. See device orientation.

ABSOLUTE MAXIMUM RATINGS ( $T_C = 25$ °C, unless otherwise noted)					
PARAMETER		SYMBOL	LIMIT	UNIT	
Drain-Source Voltage		$V_{DS}$	- 100	V	
Gate-Source Voltage		$V_{GS}$	$\pm 20$		
Continuous Drain Current	$V_{GS}$ at - 10 V	$I_D$	$T_C = 25$ °C	- 4.0	A
			$T_C = 100$ °C	- 2.8	
Pulsed Drain Current <sup>a</sup>		$I_{DM}$	- 16	W/°C	
Linear Derating Factor			0.29		
Linear Derating Factor (PCB Mount) <sup>e</sup>			0.025		
Single Pulse Avalanche Energy <sup>b</sup>		$E_{AS}$	200	mJ	
Avalanche Current <sup>a</sup>		$I_{AR}$	- 4.0	A	
Repetitive Avalanche Energy <sup>a</sup>		$E_{AR}$	4.3	mJ	
Maximum Power Dissipation	$T_C = 25$ °C	$P_D$	43	W	
	$T_A = 25$ °C		3.7		
Peak Diode Recovery $dV/dt^c$		$dV/dt$	- 5.5	V/ns	
Operating Junction and Storage Temperature Range		$T_J, T_{stg}$	- 55 to + 175	°C	
Soldering Recommendations (Peak Temperature)	for 10 s		300 <sup>d</sup>		

**Notes**

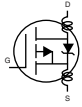
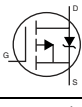
- Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).
- $V_{DD} = -25$  V, starting  $T_J = 25$  °C,  $L = 18$  mH,  $R_g = 25$   $\Omega$ ,  $I_{AS} = -4.0$  A (see fig. 12).
- $I_{SD} \leq -4.0$  A,  $dI/dt \leq 75$  A/ $\mu$ s,  $V_{DD} \leq V_{DS}$ ,  $T_J \leq 175$  °C.
- 1.6 mm from case.
- When mounted on 1" square PCB (FR-4 or G-10 material).

\* Pb containing terminations are not RoHS compliant, exemptions may apply

THERMAL RESISTANCE RATINGS				
PARAMETER	SYMBOL	TYP.	MAX.	UNIT
Maximum Junction-to-Ambient	$R_{thJA}$	-	62	°C/W
Maximum Junction-to-Ambient (PCB Mount) <sup>a</sup>	$R_{thJA}$	-	40	
Maximum Junction-to-Case (Drain)	$R_{thJC}$	-	3.5	

**Note**

a. When mounted on 1" square PCB (FR-4 or G-10 material).

SPECIFICATIONS ( $T_J = 25\text{ }^\circ\text{C}$ , unless otherwise noted)							
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX. UNIT	
<b>Static</b>							
Drain-Source Breakdown Voltage	$V_{DS}$	$V_{GS} = 0\text{ V}, I_D = -250\text{ }\mu\text{A}$		- 100	-	- V	
$V_{DS}$ Temperature Coefficient	$\Delta V_{DS}/T_J$	Reference to $25\text{ }^\circ\text{C}$ , $I_D = -1\text{ mA}$		-	- 0.091	- $V/^\circ\text{C}$	
Gate-Source Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = -250\text{ }\mu\text{A}$		- 2.0	-	- 4.0 V	
Gate-Source Leakage	$I_{GSS}$	$V_{GS} = \pm 20\text{ V}$		-	-	$\pm 100\text{ nA}$	
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS} = -100\text{ V}, V_{GS} = 0\text{ V}$		-	-	- 100 $\mu\text{A}$	
		$V_{DS} = -80\text{ V}, V_{GS} = 0\text{ V}, T_J = 150\text{ }^\circ\text{C}$		-	-	- 500 $\mu\text{A}$	
Drain-Source On-State Resistance	$R_{DS(on)}$	$V_{GS} = -10\text{ V}$	$I_D = -2.4\text{ A}^b$	-	-	1.2 $\Omega$	
Forward Transconductance	$g_{fs}$	$V_{DS} = -50\text{ V}, I_D = -2.4\text{ A}^b$		1.0	-	- S	
<b>Dynamic</b>							
Input Capacitance	$C_{iss}$	$V_{GS} = 0\text{ V}, V_{DS} = -25\text{ V}, f = 1.0\text{ MHz}$ , see fig. 5		-	200	-	pF
Output Capacitance	$C_{oss}$			-	94	-	
Reverse Transfer Capacitance	$C_{rss}$			-	18	-	
Total Gate Charge	$Q_g$	$V_{GS} = -10\text{ V}$	$I_D = -4.0\text{ A}, V_{DS} = -80\text{ V}$ , see fig. 6 and 13 <sup>b</sup>	-	-	8.7	nC
Gate-Source Charge	$Q_{gs}$			-	-	2.2	
Gate-Drain Charge	$Q_{gd}$			-	-	4.1	
Turn-On Delay Time	$t_{d(on)}$	$V_{DD} = -50\text{ V}, I_D = -4.0\text{ A}, R_g = 24\text{ }\Omega, R_D = 11\text{ }\Omega$ , see fig. 10 <sup>b</sup>		-	10	-	ns
Rise Time	$t_r$			-	27	-	
Turn-Off Delay Time	$t_{d(off)}$			-	15	-	
Fall Time	$t_f$			-	17	-	
Internal Drain Inductance	$L_D$	Between lead, 6 mm (0.25") from package and center of die contact 		-	4.5	-	nH
Internal Source Inductance	$L_S$			-	7.5	-	
<b>Drain-Source Body Diode Characteristics</b>							
Continuous Source-Drain Diode Current	$I_S$	MOSFET symbol showing the integral reverse p - n junction diode 		-	-	- 4.0	A
Pulsed Diode Forward Current <sup>a</sup>	$I_{SM}$			-	-	- 16	
Body Diode Voltage	$V_{SD}$	$T_J = 25\text{ }^\circ\text{C}, I_S = -4.0\text{ A}, V_{GS} = 0\text{ V}^b$		-	-	- 5.5	V
Body Diode Reverse Recovery Time	$t_{rr}$	$T_J = 25\text{ }^\circ\text{C}, I_F = -4.0\text{ A}, di/dt = 100\text{ A}/\mu\text{s}^b$		-	82	160	ns
Body Diode Reverse Recovery Charge	$Q_{rr}$			-	0.15	0.30	$\mu\text{C}$
Forward Turn-On Time	$t_{on}$	Intrinsic turn-on time is negligible (turn-on is dominated by $L_S$ and $L_D$ )					

**Notes**

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).
- b. Pulse width  $\leq 300\text{ }\mu\text{s}$ ; duty cycle  $\leq 2\%$ .

## TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

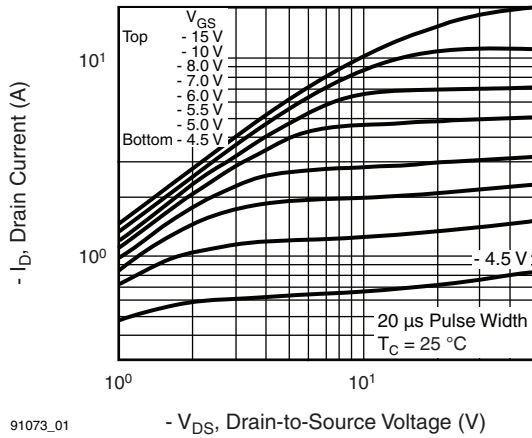


Fig. 1 - Typical Output Characteristics,  $T_C = 25\text{ }^\circ\text{C}$

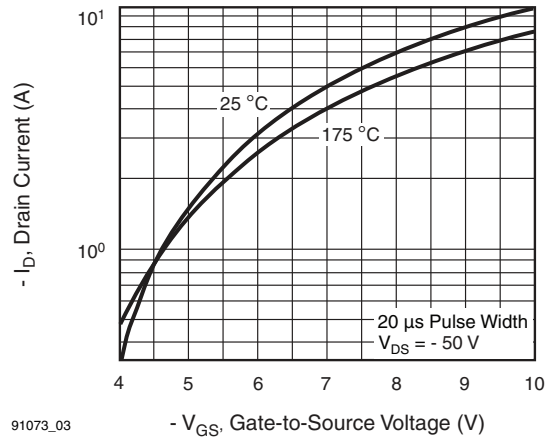


Fig. 3 - Typical Transfer Characteristics

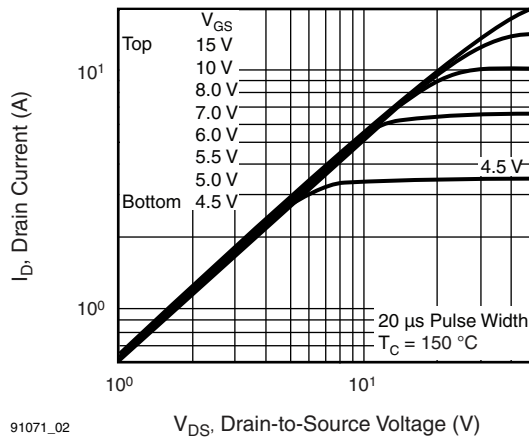


Fig. 2 - Typical Output Characteristics,  $T_C = 175\text{ }^\circ\text{C}$

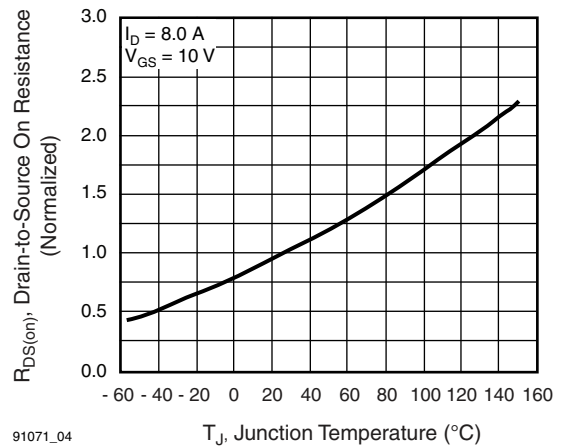
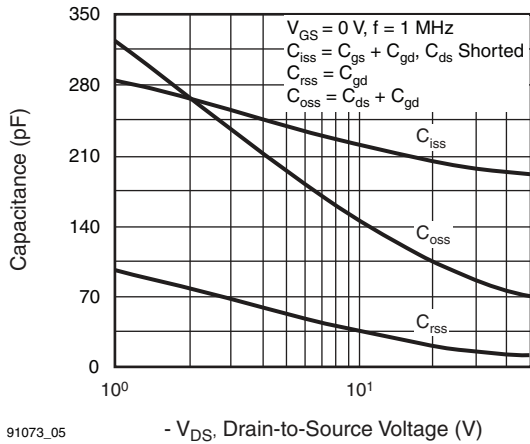
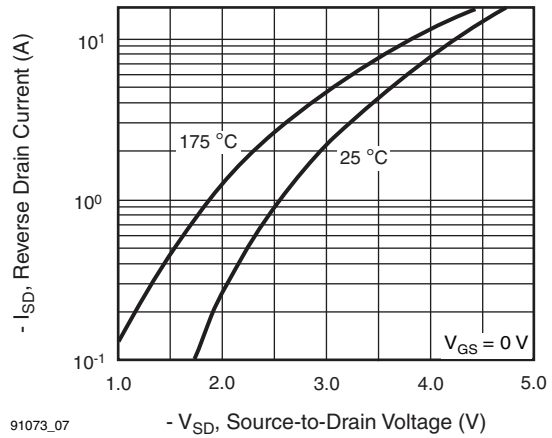


Fig. 4 - Normalized On-Resistance vs. Temperature



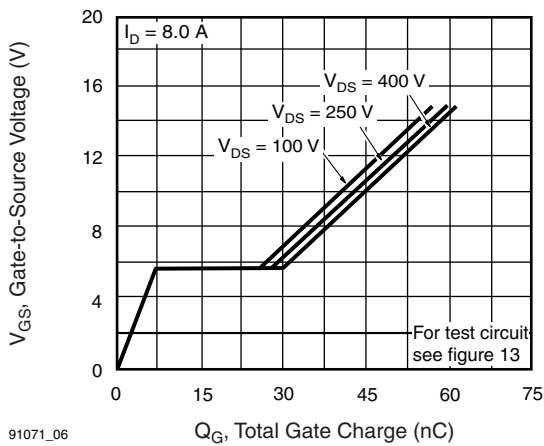
91073\_05

**Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage**



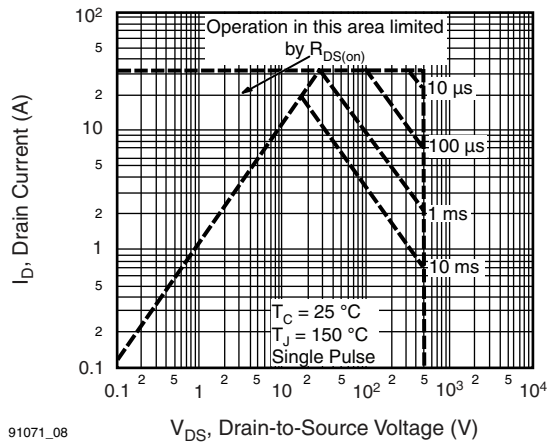
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**Fig. 7 - Typical Source-Drain Diode Forward Voltage**



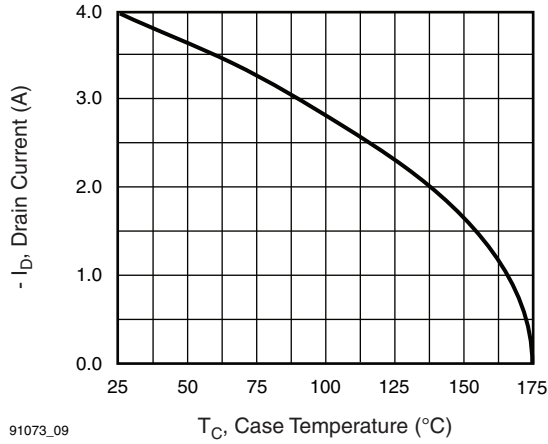
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**Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage**



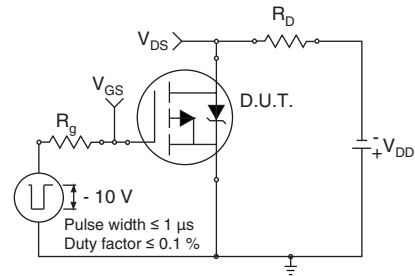
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**Fig. 8 - Maximum Safe Operating Area**

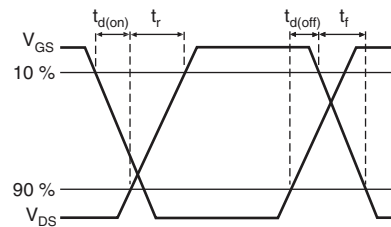


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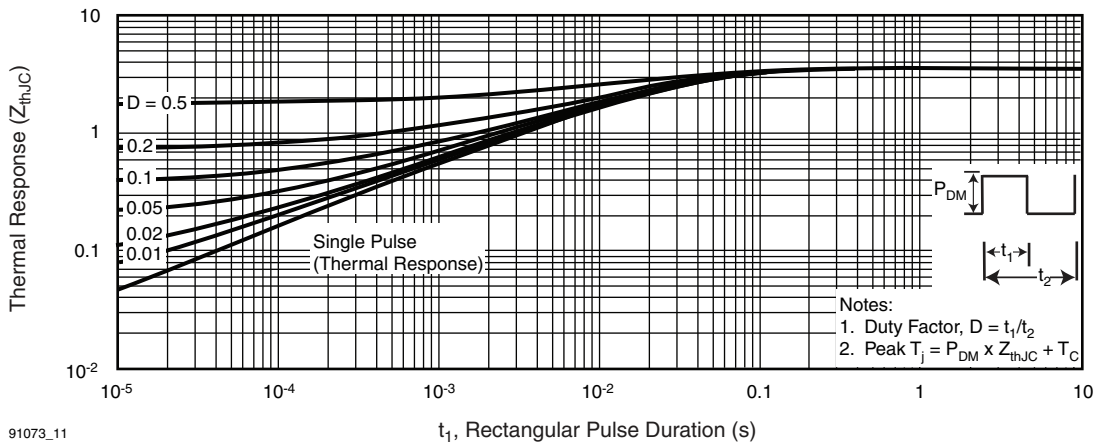
**Fig. 9 - Maximum Drain Current vs. Case Temperature**



**Fig. 10a - Switching Time Test Circuit**

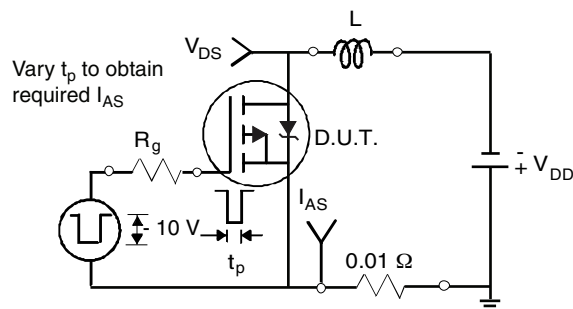


**Fig. 10b - Switching Time Waveforms**

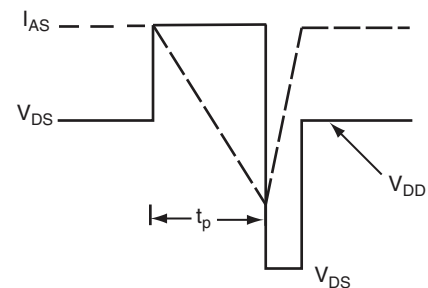


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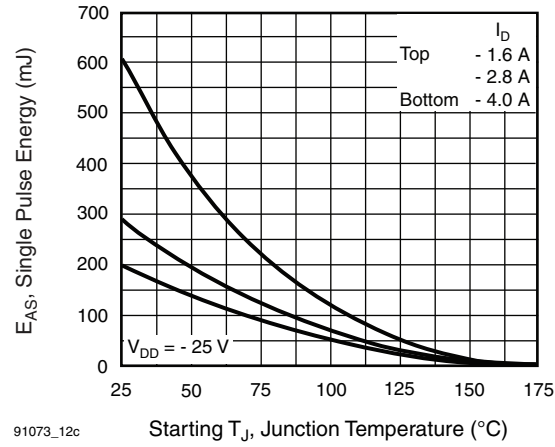
**Fig. 11 - Maximum Effective Transient Thermal Impedance, Junction-to-Case**



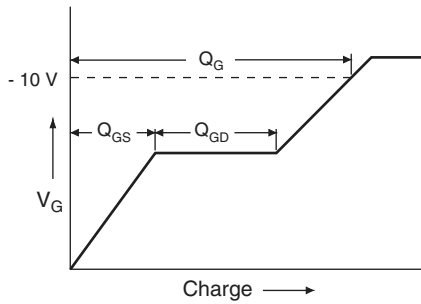
**Fig. 12a - Unclamped Inductive Test Circuit**



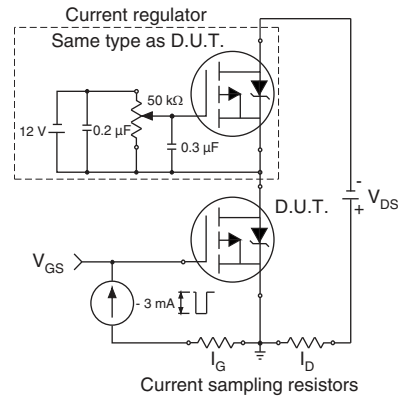
**Fig. 12b - Unclamped Inductive Waveforms**



**Fig. 12c - Maximum Avalanche Energy vs. Drain Current**

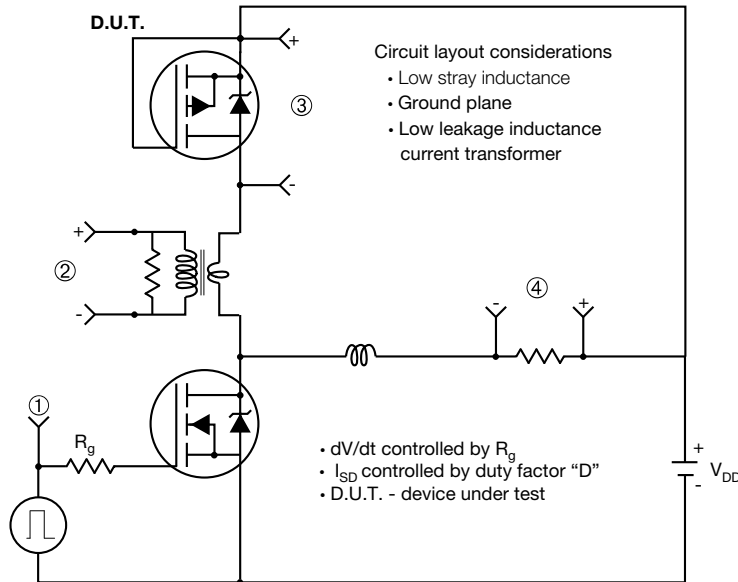


**Fig. 13a - Basic Gate Charge Waveform**

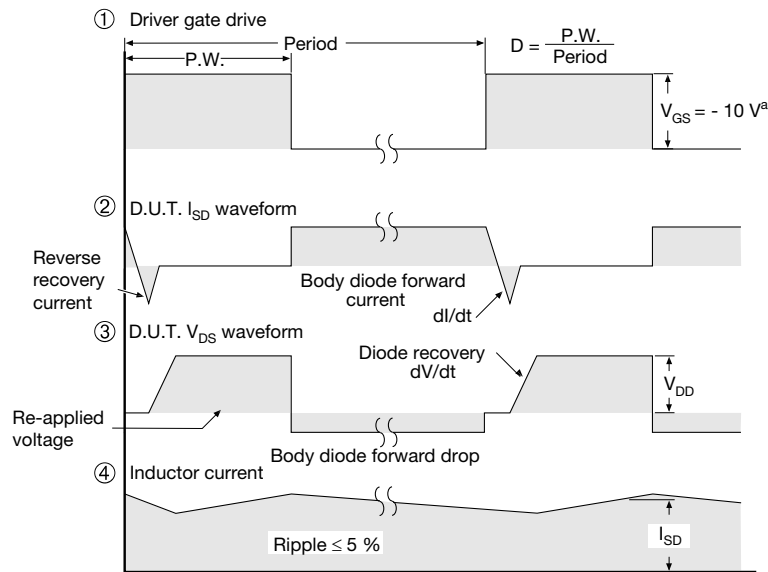


**Fig. 13b - Gate Charge Test Circuit**

### Peak Diode Recovery dV/dt Test Circuit



**Note**  
• Compliment N-Channel of D.U.T. for driver



**Note**  
a.  $V_{GS} = -5 V$  for logic level and  $-3 V$  drive devices

**Fig. 14 - For P-Channel**

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see [www.vishay.com/ppg?91073](http://www.vishay.com/ppg?91073).

### TO-263AB (HIGH VOLTAGE)



DIM.	MILLIMETERS		INCHES	
	MIN.	MAX.	MIN.	MAX.
A	4.06	4.83	0.160	0.190
A1	0.00	0.25	0.000	0.010
b	0.51	0.99	0.020	0.039
b1	0.51	0.89	0.020	0.035
b2	1.14	1.78	0.045	0.070
b3	1.14	1.73	0.045	0.068
c	0.38	0.74	0.015	0.029
c1	0.38	0.58	0.015	0.023
c2	1.14	1.65	0.045	0.065
D	8.38	9.65	0.330	0.380

DIM.	MILLIMETERS		INCHES	
	MIN.	MAX.	MIN.	MAX.
D1	6.86	-	0.270	-
E	9.65	10.67	0.380	0.420
E1	6.22	-	0.245	-
e	2.54 BSC		0.100 BSC	
H	14.61	15.88	0.575	0.625
L	1.78	2.79	0.070	0.110
L1	-	1.65	-	0.066
L2	-	1.78	-	0.070
L3	0.25 BSC		0.010 BSC	
L4	4.78	5.28	0.188	0.208

ECN: S-82110-Rev. A, 15-Sep-08  
DWG: 5970

#### Notes

1. Dimensioning and tolerancing per ASME Y14.5M-1994.
2. Dimensions are shown in millimeters (inches).
3. Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body at datum A.
4. Thermal PAD contour optional within dimension E, L1, D1 and E1.
5. Dimension b1 and c1 apply to base metal only.
6. Datum A and B to be determined at datum plane H.
7. Outline conforms to JEDEC outline to TO-263AB.



**RECOMMENDED MINIMUM PADS FOR D<sup>2</sup>PAK: 3-Lead**



Recommended Minimum Pads  
Dimensions in Inches/(mm)

[Return to Index](#)



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## Material Category Policy

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**Please note that some Vishay documentation may still make reference to RoHS Directive 2002/95/EC. We confirm that all the products identified as being compliant to Directive 2002/95/EC conform to Directive 2011/65/EU.**

**Vishay Intertechnology, Inc. hereby certifies that all its products that are identified as Halogen-Free follow Halogen-Free requirements as per JEDEC JS709A standards. Please note that some Vishay documentation may still make reference to the IEC 61249-2-21 definition. We confirm that all the products identified as being compliant to IEC 61249-2-21 conform to JEDEC JS709A standards.**



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- Оперативные поставки широкого спектра электронных компонентов отечественного и импортного производства напрямую от производителей и с крупнейших мировых складов;
- Поставка более 17-ти миллионов наименований электронных компонентов;
- Поставка сложных, дефицитных, либо снятых с производства позиций;
- Оперативные сроки поставки под заказ (от 5 рабочих дней);
- Экспресс доставка в любую точку России;
- Техническая поддержка проекта, помощь в подборе аналогов, поставка прототипов;
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- Лицензия ФСБ на осуществление работ с использованием сведений, составляющих государственную тайну;
- Поставка специализированных компонентов (Xilinx, Altera, Analog Devices, Intersil, Interpoint, Microsemi, Aeroflex, Peregrine, Syfer, Eurofarad, Texas Instrument, Miteq, Cobham, E2V, MA-COM, Hittite, Mini-Circuits, General Dynamics и др.);

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- Подбор аналогов;
- Консультации по применению компонента;
- Поставка образцов и прототипов;
- Техническая поддержка проекта;
- Защита от снятия компонента с производства.



#### Как с нами связаться

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**Факс:** 8 (812) 320-02-42

**Электронная почта:** [org@eplast1.ru](mailto:org@eplast1.ru)

**Адрес:** 198099, г. Санкт-Петербург, ул. Калинина, дом 2, корпус 4, литера А.